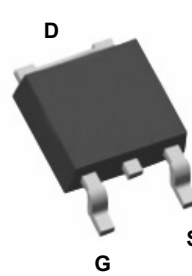
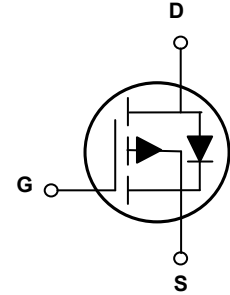


**Main Product Characteristics**

$V_{DS}$	-60V
$R_{DS(ON)}$	40mΩ
$I_D$	-26A



TO-252 (DPAK)



Schematic Diagram

**Features and Benefits**

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



**Description**

The SSFD6035 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

**Absolute Maximum Ratings** ( $T_A=25^{\circ}C$  unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous (25°C)	$I_D$	-26	A
Drain Current-Continuous (70°C)		-20	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-60	A
Maximum Power Dissipation	$P_D$	60	W
Thermal Resistance, Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$	25	°C/W
Operating Junction Temperature Range	$T_J$	-55 To +175	°C
Storage Temperature Range	$T_{STG}$	-55 To +175	°C

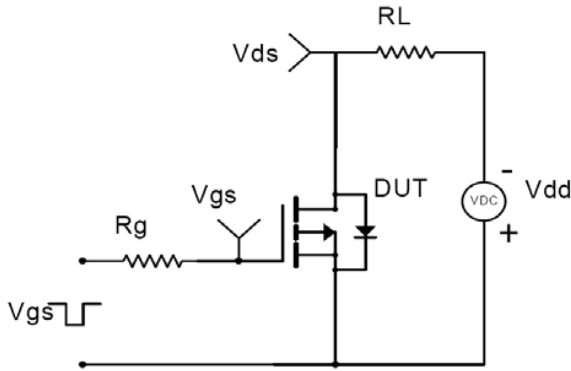
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On/Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-48V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-20A$	-	31	40	m $\Omega$
		$V_{GS}=-4.5V, I_D=-20A$	-	42	55	
Gate Threshold Voltage <sup>3</sup>	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1	-1.8	-2.5	V
Forward Transconductance <sup>3</sup>	$g_{fs}$	$V_{DS}=-5V, I_D=-20A$	5	-	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>4</sup>	$Q_g$	$V_{DS}=-30V,$ $I_D=-20A, V_{GS}=-10V$	-	48	-	nC
Gate-Source Charge <sup>4</sup>	$Q_{gs}$		-	11	-	
Gate-Drain Charge <sup>4</sup>	$Q_{gd}$		-	10	-	
Turn-On Delay Time <sup>4</sup>	$t_{d(on)}$	$V_{DS}=-30V,$ $R_{GEN}=3\Omega,$ $V_{GS}=-10V, I_D=1A$	-	14	-	nS
Rise Time <sup>4</sup>	$t_r$		-	20	-	
Turn-Off Delay Time <sup>4</sup>	$t_{d(off)}$		-	40	-	
Fall Time <sup>4</sup>	$t_f$		-	19	-	
Input Capacitance	$C_{iss}$	$V_{DS}=-30V,$ $V_{GS}=0V, F=1MHz$	-	3060	-	pF
Output Capacitance	$C_{oss}$		-	300	-	
Reverse Transfer Capacitance	$C_{rss}$		-	205	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Diode Forward Voltage <sup>3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=-1A$	-	-0.72	-1	V

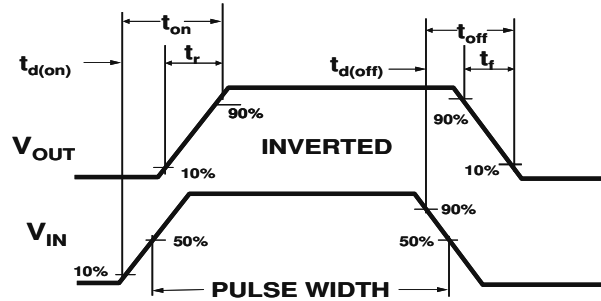
**NOTES:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on 1in<sup>2</sup> FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production testing.

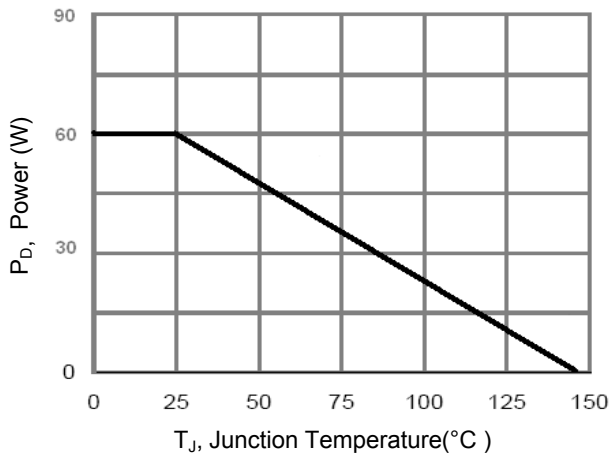
**Typical Electrical and Thermal Characteristics**



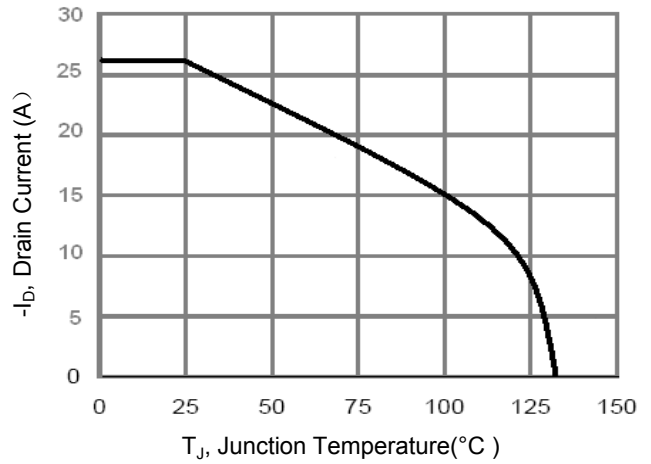
**Figure 1. Switching Test Circuit**



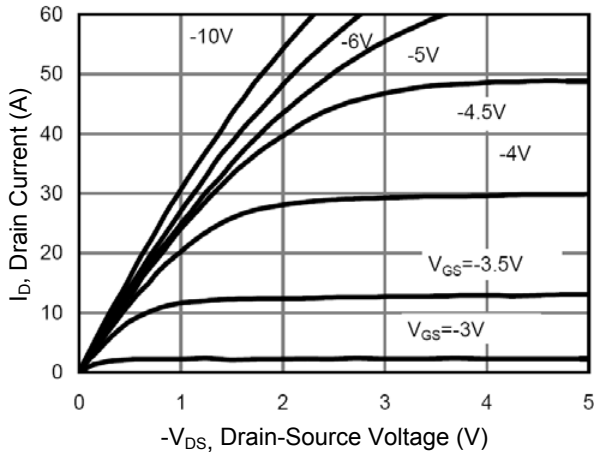
**Figure 2. Switching Waveforms**



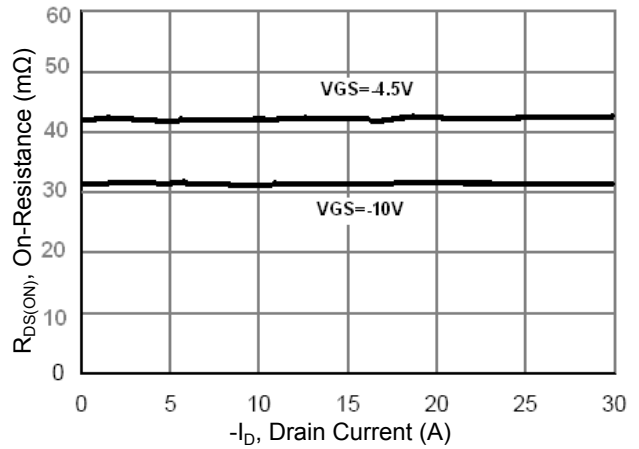
**Figure 3. Power Dissipation**



**Figure 4. Drain Current**

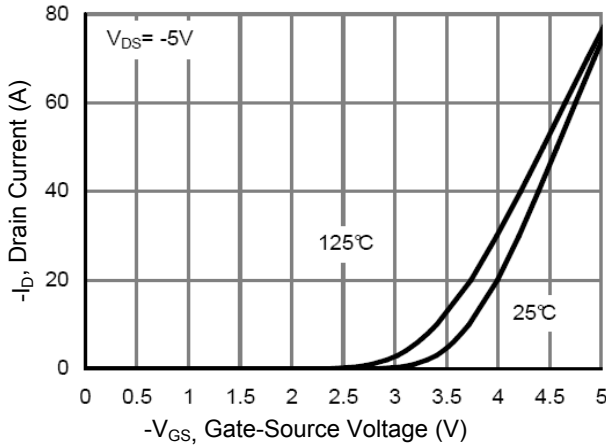


**Figure 5. Output Characteristics**

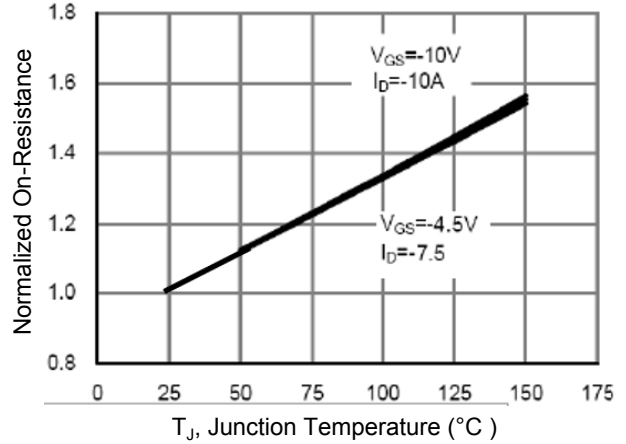


**Figure 6. Drain-Source On-Resistance**

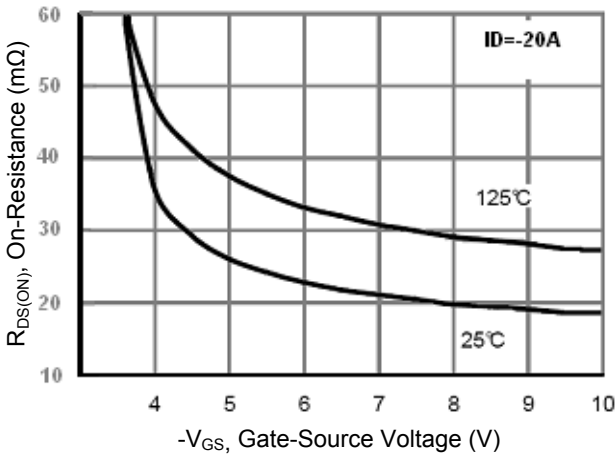
**Typical Electrical and Thermal Characteristics**



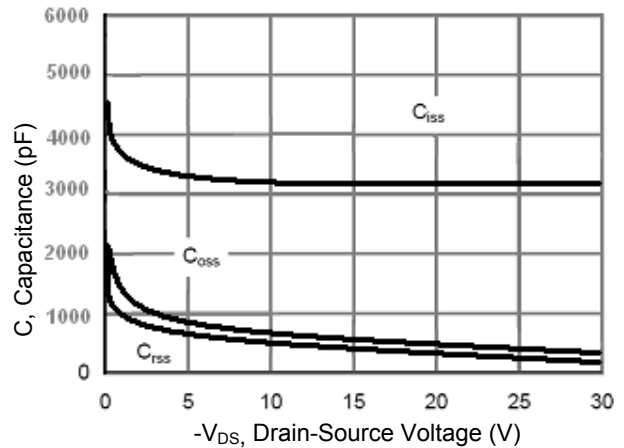
**Figure 7. Transfer Characteristics**



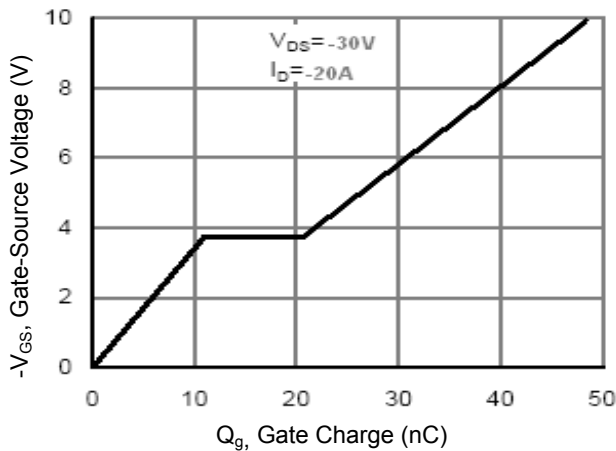
**Figure 8. Drain-Source On-Resistance**



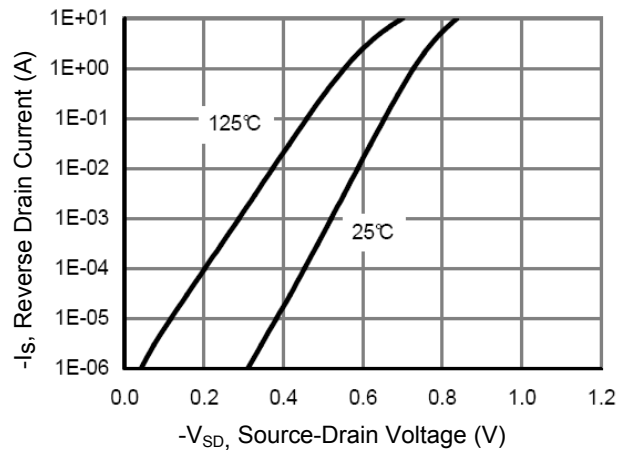
**Figure 9.  $R_{DS(ON)}$  vs  $V_{GS}$**



**Figure 10. Capacitance vs  $V_{DS}$**

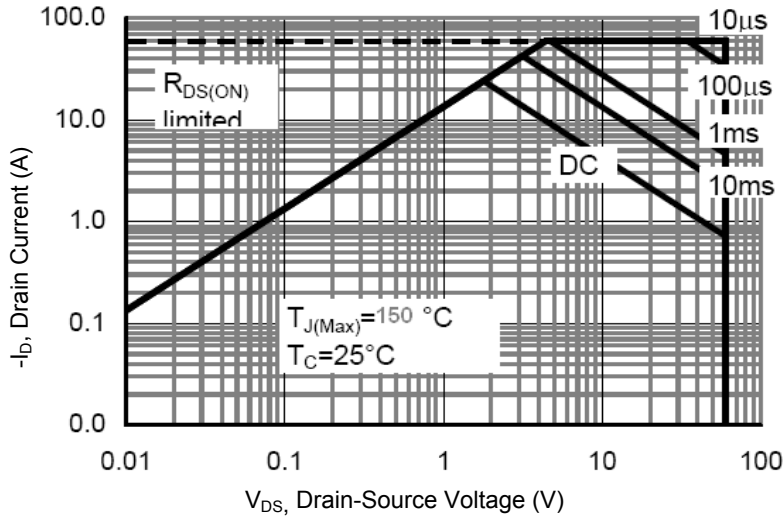


**Figure 11. Gate Charge**

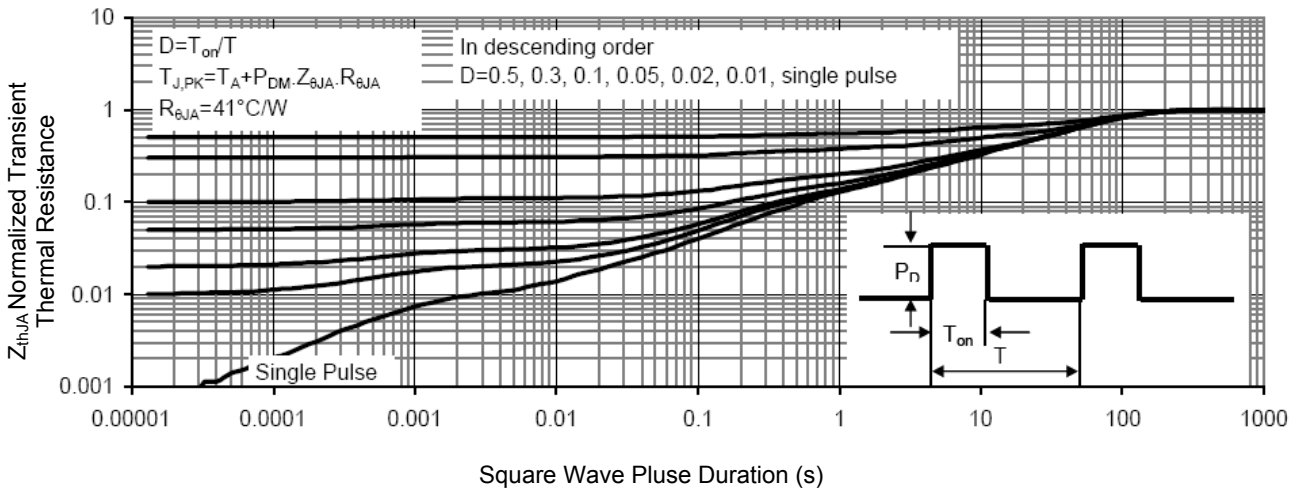


**Figure 12. Source - Drain Diode Forward Voltage**

**Typical Electrical and Thermal Characteristics**

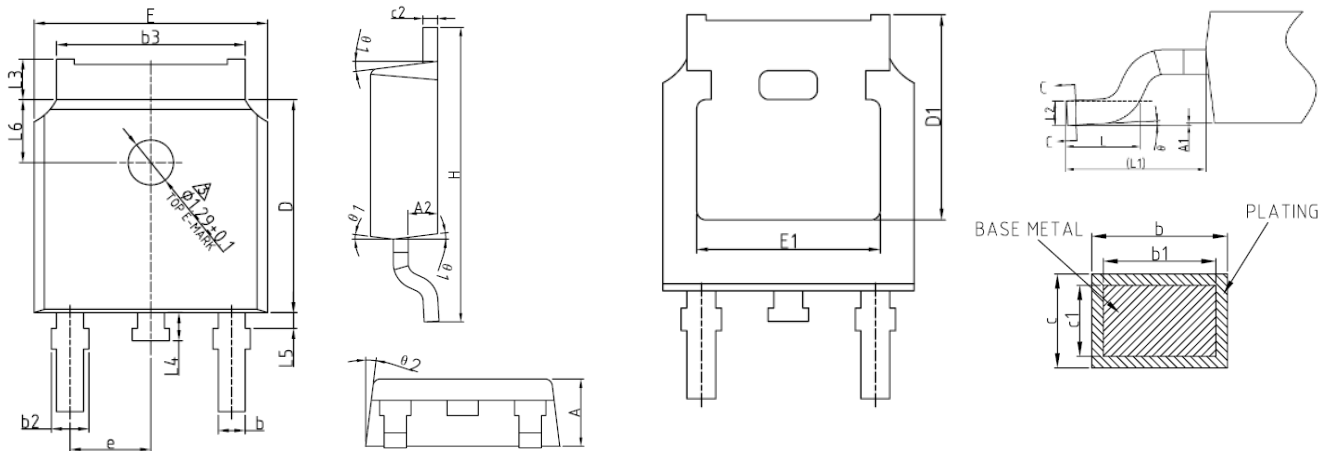


**Figure 13. Safe Operation Area**



**Figure 14. Normalized Maximum Transient Thermal Impedance**

**Package Outline Dimensions (TO-252/DPAK)**



Symbol	Dimensions in Millimeters (Unit:mm)			Symbol	Dimensions in Millimeters (Unit:mm)		
	Min	Nom	Max		Min	Nom	Max
A	2.20	2.30	2.38	E1	4.70	-	-
A1	0.00	-	0.10	e	2.186	2.286	2.386
A2	0.90	1.01	1.10	H	9.80	10.10	10.40
b	0.72	-	0.85	L	1.40	1.50	1.70
b1	0.71	0.76	0.81	L1	2.90 REF		
b2	0.72	-	0.90	L2	0.51 BSC		
b3	5.13	5.33	5.46	L3	0.90	-	1.25
c	0.47	-	0.60	L4	0.60	0.80	1.00
c1	0.46	0.51	0.56	L5	0.15	-	0.75
c2	0.47	-	0.60	L6	1.80 REF		
D	6.00	6.10	6.20	θ	0°	-	8°
D1	5.25	-	-	θ1	5°	7°	9°
E	6.50	6.60	6.70	θ2	5°	7°	9°

**NOTES:**

1. Dimensions are inclusive of plating
2. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 6 mils.
3. Dimension L is measured in gauge plane.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.